

Continuation of Serial No.: 09/503,249

IN THE SPECIFICATION

Please add the following new paragraph on Page 1, before line 3:

--This application is a continuation application of U.S. Application Serial No. 09/503,249, now U.S. Patent 6,610,166 issued August 26, 2003, which is a continuation application of U.S. Application Serial No. 08/943,274, now U.S. Patent No. 6,096,155 to August 1, 2000, which are hereby incorporated by reference in their entirety for all purposes.--

On page 8, please replace the paragraph in lines 15-16 with:

--Figs. 4A-4B illustrate specific examples of bonding two substrate together;--

On page 8, please delete the paragraph of lines 19-20 and insert therefor

--Fig. 6A illustrates embossing an embossable material onto a support substrate using a master element;

Fig. 6B illustrates embossing an embossable material on a support substrate using a master element;--

On page 16, line 25-page 17, line 23, please delete the paragraphs and insert therefor:

Alternatively, these photolithographic techniques may be used to make a master element 48 in glass which in turn may then be used to stamp out the desired element on a wafer level in a layer of embossable material 50 onto a substrate 52 as shown in Fig. 6B. The layer 50 is preferably a polymer, while the substrate 52 is can be glass, e.g., fused silica, or plastic, preferably polycarbonate or acrylic. The polymer is preferably a UV curable acrylate photopolymer having good release from a master and good adherence to a substrate such that it does not crack after cure or release from the substrate during dicing. Suitable polymers

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include PHILIPS type 40029 Resin or GAFGARD 233. Dashed lines 58 indicate the dicing lines for forming an individual integrated element from the wafer.

In the embodiment shown in Figure 6A, the layer of embossable material 50 is provided on the master element 48. A layer of adhesion promoter 54 is preferably provided on the substrate 52 and/or a layer of a release agent is provided on the master element 48 in between the master element and the embossing material. The use of an adhesion promoter and/or release agent is of particular importance when the master and the substrate are of the same material or when the master naturally has a higher affinity for adhesion to the embossable material.--

On page 14, please replace the paragraph in lines 18-25 with:

--A specific example of integrated multiple optical elements is shown in Fig. 4A. A refractive 20 is formed on a surface of the first substrate 12. A diffractive 22 is formed on a surface of the other substrate 10. A diffractive 28 may also be formed on a bottom surface of either substrate. The stand offs 16 forming the trenches for receiving the adhesive 14 are formed at the same time as a refractive lens.

Another specific example of integrated multiple optical elements is shown in Fig. 4B. An active element 25, e.g., a laser, is provided on the first substrate 12. The first substrate 12 may be etched to provide a reflective surface 27, 17 therein. The second substrate 11, which has been separated to form dies with diffractive elements 22 thereon, may be mounted to the first substrate 12 via the adhesive 12. Stand-offs 29 may be provided to insure alignment between the reflective surface 27, 17, the active element 25 and the diffractive element 22.--